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Field Device Integration (FDI) - Part 7: Communication Devices

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/23

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NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN IEC 62769-7**

May 2023

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Supersedes EN IEC 62769-7:2021

English Version

**Field Device Integration (FDI®) - Part 7: Communication Devices  
(IEC 62769-7:2023)**

Intégration des appareils de terrain (FDI®) - Partie 7:  
Appareils de Communication  
(IEC 62769-7:2023)

Feldgeräteintegration (FDI®) - Teil 7: FDI-  
Kommunikationsgeräte  
(IEC 62769-7:2023)

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## EN IEC 62769-7:2023 (E)

### European foreword

The text of document 65E/859/CDV, future edition 3 of IEC 62769-7, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-7:2023.

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 61804-4	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 4: EDD interpretation	EN IEC 61804-4	-
IEC/TR 62541-1	-	OPC unified architecture - Part 1: Overview and concepts	-	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-6	-	OPC Unified Architecture - Part 6: Mappings	EN IEC 62541-6	-
IEC 62541-7	-	OPC unified architecture - Part 7: Profiles	EN IEC 62541-7	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-1	-	Field Device Integration (FDI®) - Part 1: Overview	EN IEC 62769-1	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-3	-	Field Device Integration (FDI®) - Part 3: Server	EN IEC 62769-3	-
IEC 62769-4	2023	Field Device Integration (FDI®) - Part 4: FDI Packages	EN IEC 62769-4	2023
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	EN IEC 62769-5	-



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# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field Device Integration (FDI®) –  
Part 7: Communication Devices**

**Intégration des appareils de terrain (FDI®) –  
Partie 7: Appareils de Communication**





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Edition 3.0 2023-04

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field Device Integration (FDI®) –  
Part 7: Communication Devices**

**Intégration des appareils de terrain (FDI®) –  
Partie 7: Appareils de Communication**

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## FIELD DEVICE INTEGRATION (FDI®) –

### Part 7: Communication Devices

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IEC 62769-7 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added ScanExtended Method.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/859/CDV	65E/916/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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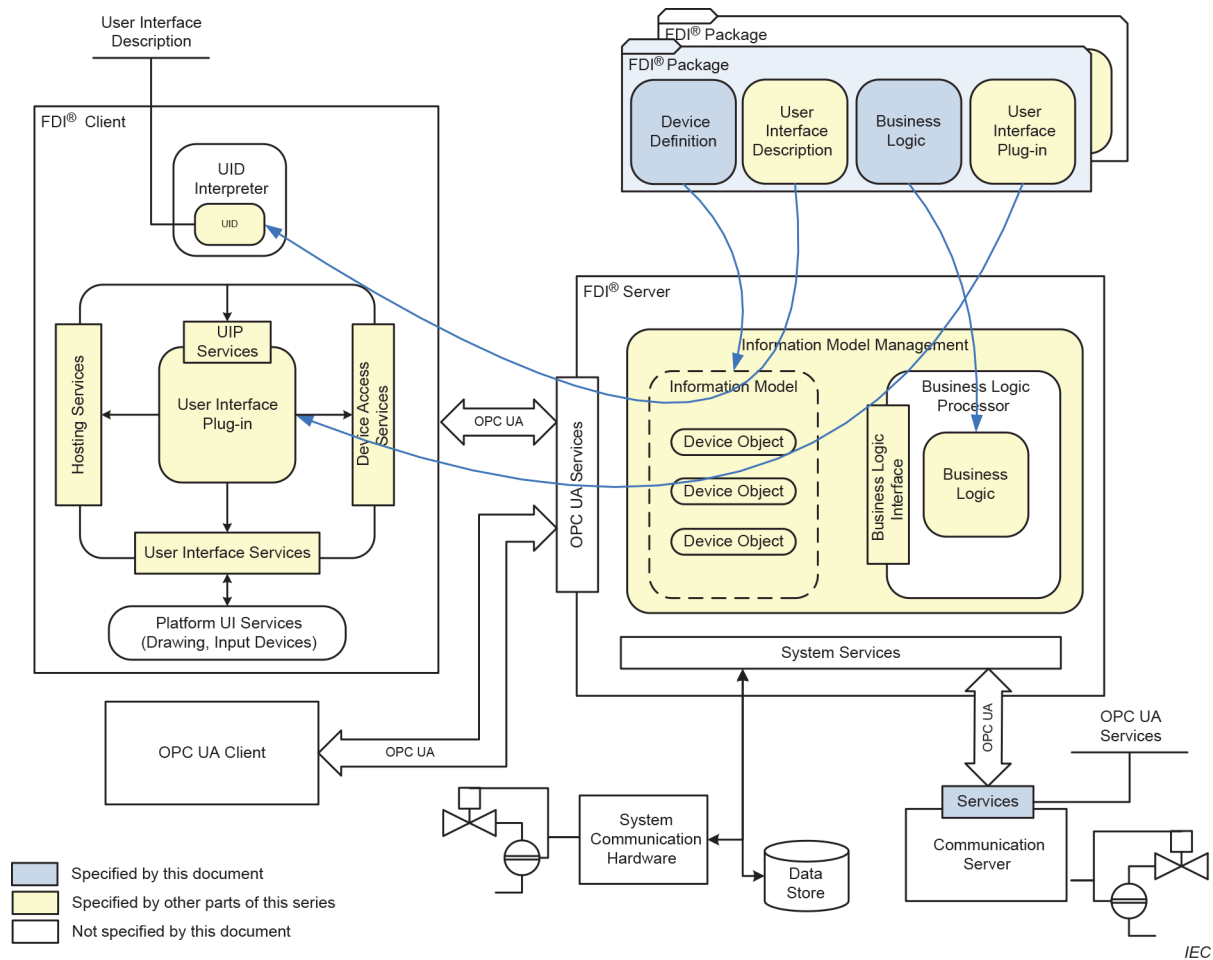
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# FIELD DEVICE INTEGRATION (FDI®) – Part 7: Communication Devices

## 1 Scope

This part of IEC 62769 specifies the elements implementing communication capabilities called Communication Devices.

The overall FDI®<sup>1</sup> architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration. The document scope with respect to FDI® Packages is limited to Communication Devices. The Communication Server shown in Figure 1 is an example of a specific Communication Device.



**Figure 1 – FDI® architecture diagram**

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